



MYPro series MY300™ pick-and-place



Specifications

MY300EX™

pick-and-place

March 2019

MYPro series specification – MY300EX

PLACEMENT SPEED AND ACCURACY

PLACEMENT SPEED AND ACCURACY – MY300EX-9/13	
Rated speed ⁽¹⁾	11 000 CPH
IPC 9850 chip net throughput ^(2, 3)	10 000 CPH
IPC 9850 chip tact time ⁽³⁾	0.36 s
IPC 9850 chip repeatability 3σ (X, Y, Theta) ⁽³⁾	30 μm, 1.8°
IPC 9850 chip accuracy @ Cpk = 1.33 (X, Y, Theta) ⁽⁵⁾	50 μm, 2.6°
IPC 9850 fine pitch repeatability 3σ (X, Y, Theta) ⁽⁴⁾	21 μm, 0.05°
IPC 9850 fine pitch accuracy @ Cpk = 1.33 (X, Y, Theta) ^(4, 5)	35 μm, 0.09°

The IPC 9850 net throughput and accuracy numbers are obtained simultaneously, with the same machine settings. The rated speed value is obtained under conditions optimized for speed.

- (1) Optimal conditions.
- (2) According to IPC 9850. Net throughput = (no of parts x 3600) / (board build time + board transfer time).
- (3) According to IPC 9850 0402C verification panel.
- (4) See document P-010-0112-EN for details.
- (5) According to IPC 9850 Cpk 1.33 = 4σ + offset.

SYSTEM FEATURES

SYSTEM FEATURES MY300EX
On-the-fly mount order optimization
Vision autoteach with snap-to-grid
Automatic illumination settings
Intelligent feeder concept – Agilis
Automatic feeder and component recognition
On-the-fly feeder loading
Dynamic feeder positions
Automatic board stretch compensation
Automatic conveyor width adjustment
Intelligent surface impact control
Tool collision avoidance
Multi-user, multi-tasking system software
Open software interfaces for factory integration
SQL database engine
Programmable light settings fiducial camera

FEEDER CAPACITY

	FEEDER CAPACITY 8 MM TAPE	
	T460	T640
MY300EX-9	96	N/A
MY300EX-13	160	144

BOARD HANDLING

	INLINE CONVEYOR	
	T460	T640
Maximum board size	460 x 510 mm (18" x 20")	640 x 510 mm (25" x 20")
Minimum board size ⁽¹⁾	70 x 50 mm (2.7" x 2")	70 x 50 mm (2.7" x 2")
Board thickness range ⁽¹⁾	0.4 – 6.0 mm (0.016" – 0.24")	0.4 – 6.0 mm (0.016" – 0.24")
Board edge clearance top	3.2 mm (0.13")	3.2 mm (0.13")
Board edge clearance bottom ⁽²⁾	3.2 mm (0.13")	3.2 mm (0.13")
Top side clearance (max)	35 mm (1.38")	35 mm (1.38")
Bottom side clearance (max) ⁽³⁾	32 mm (1.25")	32 mm (1.25")
Maximum board weight	4 kg (8.8 lbs)	4 kg (8.8 lbs)
Board transfer height	Conforms to SMEMA standard for board transfer height. Height adjustable from 880 to 975 mm (34.6" to 38.4").	
Operation mode	Inline, manual, inline odd-board, left-to-right / right-to-left.	

- (1) Board train specification: 90 x 50 mm (3.5" x 2") min board size, 1.6 mm (0.06") min thickness. Max warpage 1 mm (0.04"). Max board train length 460 mm (18") on both T460 and T640.
- (2) Edge clearance 5.5 mm (0.22") if component taller than 6 mm (0.24"), 14.3 mm (0.56") if taller than 19 mm (0.75").
- (3) 15 mm (0.59") with support pins.

COMPONENT RANGE

HIGH PRECISION MOUNTHEAD – MIDAS	
Component range	Chip (from 03015), SOIC, PLCC, TSOP, QFP, BGA, flip chip, odd-shape, surface-mount connectors, through-hole components, CSP, CCGA, DPAK, Alcap, Tantalum
Component specification	Min: 0.3 x 0.15 (0.012" x 0.006") (03015) Max: 140 x 73 x 35 mm (5.51" x 2.87" x 1.38") ⁽¹⁾ Max: component weight: 140 g ⁽²⁾

- (1) With 4K vision. Max component size with 2K vision: 140 x 56 x 35 mm (5.51" x 2.20" x 1.38").
- (2) Depending on mounthead, mount tool, package, and production altitude.

ELECTRICAL VERIFIER (OPTIONAL)	
Component range	Resistor, capacitor, unipolar capacitor, diode (forward voltage, reverse current), Zener diode (voltage drop), transistor (current gain)

VISION CAPABILITY

LINESCAN VISION SYSTEM - 4K RESOLUTION		
COMPONENT TYPE	MIN PITCH	MIN LEAD WIDTH
Leaded components	0.10 mm (4 mil)	0.05 mm (2 mil)
Bumped components	0.15 mm (6 mil)	0.08 mm (3 mil)

LINESCAN VISION SYSTEM - 2K RESOLUTION		
COMPONENT TYPE	MIN PITCH	MIN LEAD WIDTH
Leaded components	0.20 mm (8 mil)	0.10 mm (4 mil)
Bumped components	0.25 mm (10 mil)	0.13 mm (5 mil)

SOFTWARE

SOFTWARE MODULES (OPTIONAL)

Shared databases
Line mode
PCB ID (2D barcode)
Pre-pick inspection
Barcode software
PRM software

OFFLINE SOFTWARE TOOLS (OPTIONAL)

Data preparation - MYCenter
Optimization and scheduling - MYPlan
Inventory management and kitting - MYCenter
Traceability - MYTrace

MISCELLANEOUS

INSTALLATION REQUIREMENTS

Power requirements	Three phase AC 6.6 kVA (3 x 2.2 kVA)
Power consumption	1.5 kW (average)
Voltages	3 x 200, 210, 220, 230, 240, 250 +/- 10%, Y or Delta
Air supply	No air required
Noise	70 dBA
Air temperature	+18 to +35 °C (65 to 95 °F)
Air humidity	< 95% RH non condensing

MACHINE WEIGHT (1)

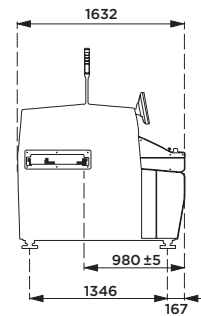
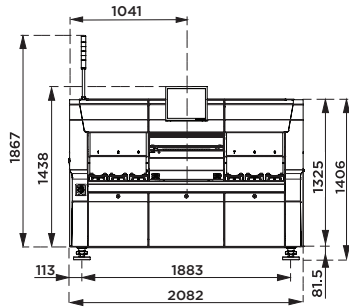
MY300EX-9	1 500 kg (3 300 lbs)
MY300EX-13	1 600 kg (3 500 lbs)

(1) Total machine weight excluding magazines.

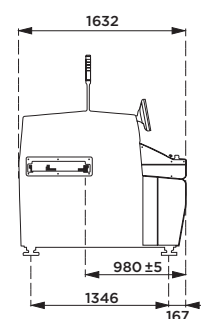
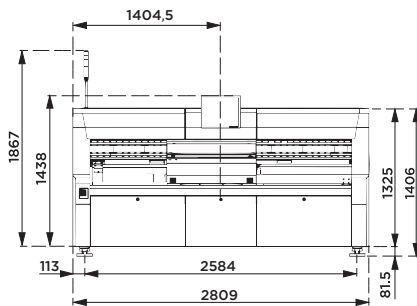
DIMENSIONS

in mm.

MY300EX-9



MY300EX-13



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